Product Change Notification - KSRA-26CDAN357

Date: 03 Apr 2017

Product Category: Memory

Notification subject: CCB 2897 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K wafer technology available in 8L TDFN package at NSEB assembly site.

Notification text:

PCN Status:
Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K wafer technology available in 8L TDFN package at NSEB assembly site.

Pre Change:
Using gold (Au) bond wire, 8200T die attach and G770HCD mold compound material.

Post Change:
Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB assembly site	NSEB assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8200T	8600
Molding compound material	G770HCD	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve manufacturability and qualify CuPdAu bond wire, 8600 die attach and G700LTD mold compound material at NSEB assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
May 15, 2017

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2017					--->	May 2017				
Workweek	09	10	11	12	13		18	19	20	21	32
Final PCN Issue Date					X						
Estimated Implementation Date									X		

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
March 31, 2017: Issued final notification.
April 3, 2017: Re-issued final notification to revise the qual report title.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-26CDAN357_Qual Report.pdf
PCN_KSRA-26CDAN357_Affected CPN.pdf
PCN_KSRA-26CDAN357_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-26CDAN357
CATALOG_PART_NBR
24AA32AT-I/MNY
24LC32AT-I/MNY
93AA46AT-I/MNY
93AA46BT-I/MNY
93AA46CT-I/MNY
93AA56AT-I/MNY
93AA56BT-I/MNY
93AA56CT-I/MNY
93AA66AT-I/MNY
93AA66BT-I/MNY
93AA66CT-I/MNY
93AA76CT-I/MNY
93AA86CT-I/MNY
93C46AT-E/MNY
93C46AT-I/MNY
93C46BT-E/MNY
93C46BT-I/MNY
93C46CT-E/MNY
93C46CT-I/MNY
93C56AT-E/MNY
93C56AT-I/MNY
93C56BT-E/MNY
93C56BT-I/MNY
93C56CT-E/MNY
93C56CT-I/MNY
93C66AT-E/MNY
93C66AT-I/MNY
93C66BT-E/MNY
93C66BT-I/MNY
93C66CT-E/MNY
93C66CT-I/MNY
93C76CT-E/MNY
93C76CT-I/MNY
93C86CT-E/MNY
93C86CT-I/MNY
93LC46AT-E/MNY
93LC46AT-I/MNY
93LC46BT-E/MNY
93LC46BT-I/MNY
93LC46CT-E/MNY
93LC46CT-I/MNY
93LC56AT-E/MNY
93LC56AT-I/MNY

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CATALOG_PART_NBR
93LC56BT-E/MNY
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93LC56CT-E/MNY
93LC56CT-I/MNY
93LC66AT-E/MNY
93LC66AT-I/MNY
93LC66BT-E/MNY
93LC66BT-I/MNY
93LC66CT-E/MNY
93LC66CT-I/MNY
93LC76CT-E/MNY
93LC76CT-I/MNY
93LC86CT-E/MNY
93LC86CT-I/MNY